



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	22-12-2022
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H725VGT6	E01L*483XXZ	A	9991	22-12-2022
	Amount	UoM	Unit type	ST ECOPACK Grade
	681.44	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14	100	L bend	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	E01L*483XXZ				6000000.0	999997.7
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	13.690	mg	supplier	die	Silicon (Si)	7440-21-3		13.190	mg	963477	19356
				supplier	metallization	Aluminium (Al)	7429-90-5		0.059	mg	4310	87
				supplier	metallization	Copper (Cu)	7440-50-8		0.186	mg	13587	273
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	73	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.030	mg	2191	44
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	365	7
Leadframe LF# C7025		185.500	mg	supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	73	1
				supplier	Passivation	Silicon Oxide	7631-86-9		0.218	mg	15924	320
				supplier	Leadframe	Copper (Cu)	7440-50-8		175.112	mg	944000	256973
				supplier	Leadframe	Silver (Ag)	7440-22-4		2.783	mg	15000	4083
				supplier	Leadframe	Magnesium (Mg)	7439-95-4		0.325	mg	1750	476
				supplier	Leadframe	Silicon (Si)	7440-21-3		1.345	mg	7250	1974
Glue (CRM 1076WA)		2.800	mg	supplier	Leadframe	Nickel (Ni)	7440-02-0		5.936	mg	32000	8711
				supplier	Glue or tape	Silver Powder	7440-22-4		2.111	mg	754000	3098
				supplier	Glue or tape	Bisphenol F Type Epoxy Resin	9003-36-5		0.084	mg	30000	123
				supplier	Glue or tape	Epoxy resin	Trade Secret		0.196	mg	70000	288
				supplier	Glue or tape	Diluent	Trade Secret		0.070	mg	25000	103
				supplier	Glue or tape	Ethylene dimethacrylate	97-90-5		0.224	mg	80000	329
Bonding wire (Au 0.8 mils)		3.000	mg	supplier	Glue or tape	1,4-Cyclohexanedimethanol diglycidyl ether	14228-73-0		0.084	mg	30000	123
				supplier	Glue or tape	Dicyandiamide	461-58-5		0.015	mg	5500	23
				supplier	Glue or tape	1,1-Di(t-butylperoxy)cyclohexane	3006-86-8		0.015	mg	5500	23
				supplier	Bonding wire	Au	7440-57-5		2.966	mg	988500	4352
				supplier	Bonding wire	Palladium	7440-05-3		0.035	mg	11500	51
				Encapsulation (EME-G6315H)		455.549	mg	supplier	Molding Compound	Epoxy Resin A	Proprietary	9.111
				supplier	Molding Compound	Epoxy Resin B	Proprietary	9.111	mg	20000	13370	
				supplier	Molding Compound	Phenol Resin	Proprietary	25.055	mg	55000	36768	
				supplier	Molding Compound	Carbon Black	1333-86-4		2.506	mg	5500	3677
				supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		341.434	mg	749500	501048
				supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		68.332	mg	150000	100276
External Plating		20.900	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		20.898	mg	999900	30667
				supplier	Matte Sn	Impurities	Proprietary		0.002	mg	100	3